



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Alan E. Delahoy

Group Art Unit: 1753

Examiner: Unknown

Serial No.: 10/635,344

Filed: August 6, 2003

For: HOLLOW CATHODE SPUTTERING APPARATUS AND
RELATED METHOD

Attorney Docket No.: ENPI 0101 PUS

**INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. § 1.97(b)**

Mail Stop Amendment
Commissioner for Patents
U.S. Patent & Trademark Office
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Sir:

In compliance with the duty of disclosure under 37 C.F.R. § 1.56 and §§ 1.97-1.98, the references listed and identified on the attached Forms PTO/SB08A and/or SB08B are being submitted herewith for consideration by the Examiner. This Statement is being filed in accordance with 37 C.F.R. § 1.97(b).

CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.8

I hereby certify that this paper, including all enclosures referred to herein, is being deposited with the United States Postal Service as first-class mail, postage pre-paid, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, U.S. Patent & Trademark Office, P.O. Box 1450, Alexandria, VA 22313-1450 on:

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While this Statement is being filed in compliance with the duty of disclosure, citation of the listed references is not to be construed as an admission that any of the references are "material" as defined under 37 C.F.R. § 1.56(b).

No copies of the listed U.S. patent references or the listed U.S. patent application publication references have been included herewith pursuant to 37 C.F.R. § 1.98(a)(2). Consideration and entry into the record of the listed references is respectfully requested.

Respectfully submitted,

Alan E. Delahoy

By: James W. Proscia
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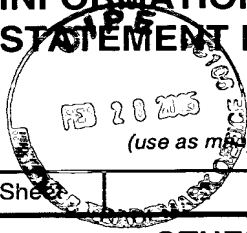
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Unique citation designation number. ² See attached Kinds of U.S. Patent Documents. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document.

⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

Substitute for Form 1449B/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT  <i>(use as many sheets as necessary)</i>		Complete if Known	
		Application Number	10/635,344
		Filing Date	August 6, 2003
		First Named Inventor	Alan E. Delahoy et al.
		Group Art Unit	1753
		Examiner Name	Unknown
Sheet 1	of 2	Attorney Docket Number	ENPI 0101 PUS
OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS			
Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		"Deposition Schemes for Low Cost Transparent Conductors for Photovoltaics", A.E. Delahoy & M. Cherny, Mat. Res. Symp. Proc., Vol. 426, 1996, pgs. 467-477	
		"High-Rate Low Kinetic Energy Gas-Flow-Sputtering System", K. Ishii, J. Vac. Sci. Technol. A, Vol. 7, No. 2, 1989, pgs. 256-258	
		"Hollow Cathode Discharge Sputtering Device for Uniform Large Area Thin Film Deposition", H. Koch, J. Vac. Sci. Technol. A., Vol. 9, No. 4, 1991, pgs. 2374-2377	
		"Zirconia Thin Film Deposition on Silicon by Reactive Gas Flow Sputtering: The Influence of Low Energy Particle Bombardment", T. Jung & A. Westphal, Mater. Sci. Eng., A140, 1991, pgs. 528-533	
		"High Rate Deposition of Alumina Films by Reactive Gas Flow Sputtering", T. Jung & A. Westphal, Surf. Coat. Technol., 59, 1993, pgs. 171-176	
		"Gas Flow Sputtering of Oxide Coatings: Practical Aspects of the Process", Th. Jung, T. Kälber, V.v.d. Heide, Surf. Coat. Technol., 86-87, 1996, pgs. 218-224	
		"New DC Sputter Sources for the Large Scale Deposition of Oxide Films", M. Höfer, A. Jung, T. Jung, H.-U. Kricheldorf & F. Schmidt, Proc. 43 rd SVC Annual Tech. Conf., 2000, pgs. 287-292	

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